

IN THE CLAIMS:

1. **(Currently Amended)** An interconnection structure of conductive wirings for interconnecting a pair of interconnection objects by a thermocompression bonding, in which the conductive wirings are disposed on the interconnection objects, respectively, comprising:

interconnection portions formed of conductive wiring patterns on a surface of each supporting body of said interconnection objects, said interconnection portions being provided with gaps between adjacent ones;

an anisotropic conductive film containing conductive particles therein, said film being interposed between said interconnection portions disposed on the respective interconnection objects; and

~~an accumulating space formed in said respective gaps between said conductive wiring patterns in order~~ to prevent an over-density of said conductive particles flown out from said interconnection portions to said gaps due to said thermocompression bonding from occurring.

2. **(Original)** The interconnection structure of conductive wirings according to claim 1, wherein said accumulating space comprises a concave portion or a hole portion formed on at least one of said supporting bodies of said interconnection objects.

3. **(Original)** The interconnection structure of conductive wirings according to claim 1, further comprising insulating layers,

wherein said insulating layers cover said supporting body of one or both of said interconnection objects except for said interconnection portion, and

wherein said accumulating space comprises retreated concave portion formed at an edge of said insulating layer adjacent to said interconnection portion.

4. **(Original)** The interconnection structure of conductive wiring according to claim 1, further comprising insulating layers,

wherein said insulating layers cover said supporting body of one or both of said interconnection objects except for said interconnection portion, and

wherein edges of said insulating layers adjacent to said interconnection portions are included in a region of said thermocompression bonding.

5. **(Original)** The interconnection structure of conductive wirings according to claim 1, wherein one of said pair of interconnection objects is a print wiring board or a TAB tape.

6. **(Original)** The interconnection structure of conductive wirings according to claim 5, wherein another one of said pair of interconnection objects is an interconnection portion of a display panel board.

7. **(Original)** The interconnection structure of conductive wirings according to claim 6, wherein said display panel board is a panel board formed of organic EL elements.

8. **(Original)** An organic EL display panel having a substrate, and interconnection portions including conductive wiring patterns formed on the substrate, in which the interconnection portions are connected with an interconnection object via an anisotropic conductive film by a thermocompression bonding, comprising:

a concave portion formed in respective gaps between said conductive wiring patterns on said substrate,

wherein said concave portion receives conductive particles flown out from said anisotropic conductive film due to the thermocompression bonding.

9. **(Original)** An organic EL display panel having a substrate, and interconnection portions including conductive wiring patterns formed on the substrate, in which the interconnection portions are connected with an interconnection object via an anisotropic conductive film by a thermocompression bonding, comprising:

a hole portion formed by penetrating said substrate in respective gaps between said conductive wiring patterns on said substrate,

wherein said hole portion receives conductive particles flown out from said anisotropic conductive film due to the thermocompression bonding.

10. **(Original)** A flexible printed-wiring board having interconnection portions including conductive wiring patterns formed on a surface thereof, in which the interconnection portions are connected with an interconnection object via an anisotropic conductive film by a thermocompression bonding, comprising:

insulating layers covered on said surface except for said interconnection portions; and

a retreated concave portion formed at each edge of said insulating layers adjacent to said interconnection portions,

wherein said retreated concave portion receives conductive particles flown out from said anisotropic conductive film due to the thermocompression bonding.

11. **(Canceled)**

12. **(New)** The interconnection structure of conductive wirings according to claim 1, wherein said accumulating space is formed in said respective gaps between said conductive wiring patterns.

13. **(New)** An interconnection structure of conductive wirings for interconnecting a pair of interconnection objects by a thermocompression bonding, in which the conductive wirings are disposed on the interconnection objects, respectively, comprising:

interconnection portions formed of conductive wiring patterns on a surface of each supporting body of said interconnection objects, said interconnection portions being provided with gaps between adjacent ones;

an anisotropic conductive film containing conductive particles therein, said film being interposed between said interconnection portions disposed on the respective interconnection objects; and

an accumulating space formed in said respective gaps between said conductive wiring patterns in order to prevent an over-density of said conductive particles flown out from said interconnection portions to said gaps due to said thermocompression bonding from occurring, wherein said accumulating space comprises a concave portion or a hole portion formed on at least one of said supporting bodies of said interconnection objects.

14. **(New)** An interconnection structure of conductive wirings for interconnecting a pair of interconnection objects by a thermocompression bonding, in which the conductive wirings are disposed on the interconnection objects, respectively, comprising:

interconnection portions formed of conductive wiring patterns on a surface of each supporting body of said interconnection objects, said interconnection portions being provided with gaps between adjacent ones;

an anisotropic conductive film containing conductive particles therein, said film being interposed between said interconnection portions disposed on the respective interconnection objects;

an accumulating space formed in said respective gaps between said conductive wiring patterns in order to prevent an over-density of said conductive particles flown out from said interconnection portions to said gaps due to said thermocompression bonding from occurring; and

insulating layers,

wherein said insulating layers cover said supporting body of one or both of said interconnection objects except for said interconnection portion, and

wherein said accumulating space comprises retreated concave portion formed at an edge of said insulating layer adjacent to said interconnection portion

15. **(New)** An interconnection structure of conductive wirings for interconnecting a pair of interconnection objects by a thermocompression bonding, in which the conductive wirings are disposed on the interconnection objects, respectively, comprising:

interconnection portions formed of conductive wiring patterns on a surface of each supporting body of said interconnection objects, said interconnection portions being provided with gaps between adjacent ones;

an anisotropic conductive film containing conductive particles therein, said film being interposed between said interconnection portions disposed on the respective interconnection objects;

an accumulating space formed in said respective gaps between said conductive wiring patterns in order to prevent an over-density of said conductive particles flown out from said interconnection portions to said gaps due to said thermocompression bonding from occurring; and

insulating layers,

wherein said insulating layers cover said supporting body of one or both of said interconnection objects except for said interconnection portion, and

wherein edges of said insulating layers adjacent to said interconnection portions are included in a region of said thermocompression bonding.